

SN54F109, SN74F109 DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

SDFS047A – MARCH 1987 – REVISED OCTOBER 1993

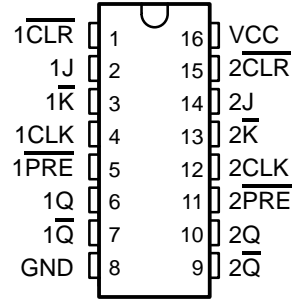
- Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

description

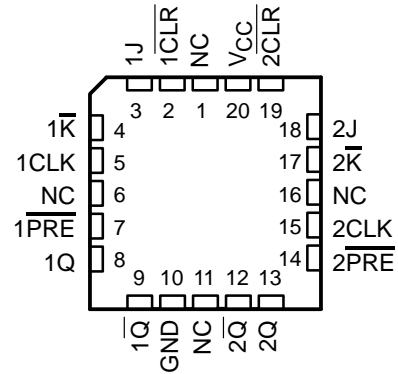
These devices contain two independent J-K positive-edge-triggered flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the J and K input meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding K and tying J high. They also can perform as D-type flip-flops if J and K are tied together.

The SN54F109 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74F109 is characterized for operation from 0°C to 70°C.

SN54F109 . . . J PACKAGE
SN74F109 . . . D OR N PACKAGE
(TOP VIEW)



SN54F109 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

INPUTS					OUTPUTS	
PRE	CLR	CLK	J	K	Q	Q-bar
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H†	H†
H	H	↑	L	L	L	H
H	H	↑	H	L	Toggle	
H	H	↑	L	H	Q ₀	Q ₀ -bar
H	H	↑	H	H	H	L
H	H	L	X	X	Q ₀	Q ₀ -bar

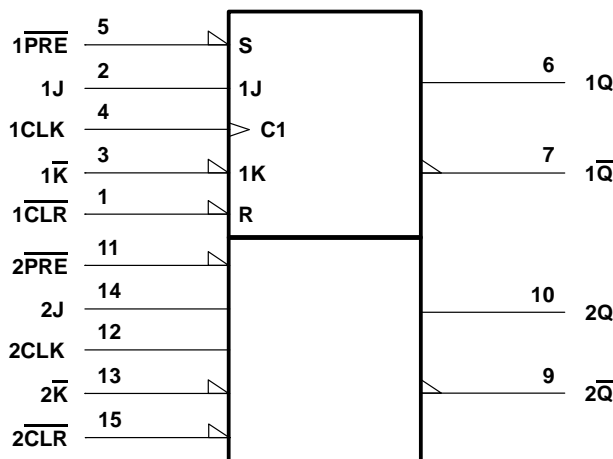
† The output levels are not guaranteed to meet the minimum levels for V_{OH}. Furthermore, this configuration is nonstable; that is, it will not persist when PRE or CLR returns to its inactive (high) level.

SN54F109, SN74F109

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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–1.2 V to 7 V
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the high state	–0.5 V to V_{CC}
Current into any output in the low state	40 mA
Operating free-air temperature range: SN54F109	–55°C to 125°C
SN74F109	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		SN54F109			SN74F109			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			–18			–18	mA
I_{OH}	High-level output current			–1			–1	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	–55		125	0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54F109			SN74F109			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$				-1.2			-1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V}$, $I_{OH} = -1\text{ mA}$		2.5	3.4		2.5	3.4		V
	$V_{CC} = 4.75\text{ V}$, $I_{OH} = -1\text{ mA}$					2.7			
V_{OL}	$V_{CC} = 4.5\text{ V}$, $I_{OL} = 20\text{ mA}$			0.3	0.5		0.3	0.5	V
I_I	$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$				0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$				20			20	μA
I_{IL}	J, \overline{K} , CLK	$V_{CC} = 5.5\text{ V}$, $V_I = 0\text{ V}$			-0.6			-0.6	mA
	\overline{PRE} or \overline{CLR}				-1.8			-1.8	
I_{OS}^\ddagger	$V_{CC} = 5.5\text{ V}$, $V_O = 0$		-60		-150	-60		-150	mA
I_{CC}	$V_{CC} = 5.5\text{ V}$, See Note 2			11.7	17		11.7	17	mA

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: I_{CC} is measured with J, \overline{K} , CLK, and \overline{PRE} grounded then with J, \overline{K} , CLK, and \overline{CLR} grounded.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$		SN54F109		SN74F109		UNIT
			'F74						
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		0	100	0	70	0	90	MHz
t _w	Pulse duration		CLK high, \overline{PRE} or \overline{CLR} low	4	4	4		ns	
			CLK low	5	5	5			
t _{su}	Setup time, data before CLK↑	High	3	3	3		ns		
		Low	3	3	3				
	Setup time, inactive-state before CLK↑§	\overline{PRE} or \overline{CLR} to CLK	2	2	2				
t _h	Hold time, data after CLK↑		High	1	1	1	ns		
			Low	1	1	1			

§ Inactive-state setup time is also referred to as recovery time.

switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, C _L = 50 pF, R _L = 500 Ω, T _A = 25°C			V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX††				UNIT
			'F109			SN54F109		SN74F109		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			100	150		70		90		MHz
t _{PLH}	CLK	Q or \overline{Q}	3	4.9	7	3	9	3	8	ns
t _{PHL}			3.6	5.8	8	3.6	10.5	3.6	9.2	
t _{PLH}	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or \overline{Q}	2.4	4.8	7	2.4	9	2.4	8	ns
t _{PHL}			2.7	6.6	9	2.7	11.5	2.7	10.5	

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 3: Load circuits and waveforms are shown in Section 1.

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